Transmitted herewith for filing is the Patent Application of:

inventor: TAI-CHUN HUANG, CHIH-HSIANG YAO, KUAN-SHOU CHI

For: NON-REPEATED AND NON-UNIFORM WIDTH SEAL RING STRUCTURE

Enclosed are:						
x	4 sheets of drawing(s) - formal.					
x	An assignment of the invention to Taiwan Semiconductor Manufacturing Co.					
	An associate power of attorney Applicant claims small entity status					
Request & Certification under 35 USC 122(b)(2)(b)(i)						
The filing fee has been calculated as shown below:						
	(Col. 1) (Col. 2)		(Col. 2)	OTHER THAN	OTHER THAN A SMALL ENTITY	
FOR:		NO. FILED	NO. EXTRA	RATE	FEE	
BASIC	FEE	><	$>\!\!<$		\$ 770.	ı
TOTAL	_CLAIMS	25 -20=	5	x 18 =	\$ 90.	
INDEP	CLAIMS	3 - 3=	0	x 86 =	\$ 0.	l
SUB 7				SUB TOTAL	\$ 860.	4
ASSIGNMENT \$					\$40.	
				TOTAL	\$ 900.	
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Any patent application processing fees under 37 CFR §1.17.

Respectfully submitted

STEEDEN B. ACKERMAN, REG. NO. 37,761

EXPRESS MAIL CERTIFICATE

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I hereby certify that this correspondence is being deposited with the United States Postal Service as Express Mail in an envelope addressed to Assistant Commissioner of Patents, Alexandria, VA, 22313-1450. Applicant and/or Attorney requests the date of deposit as the Filing Date.

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